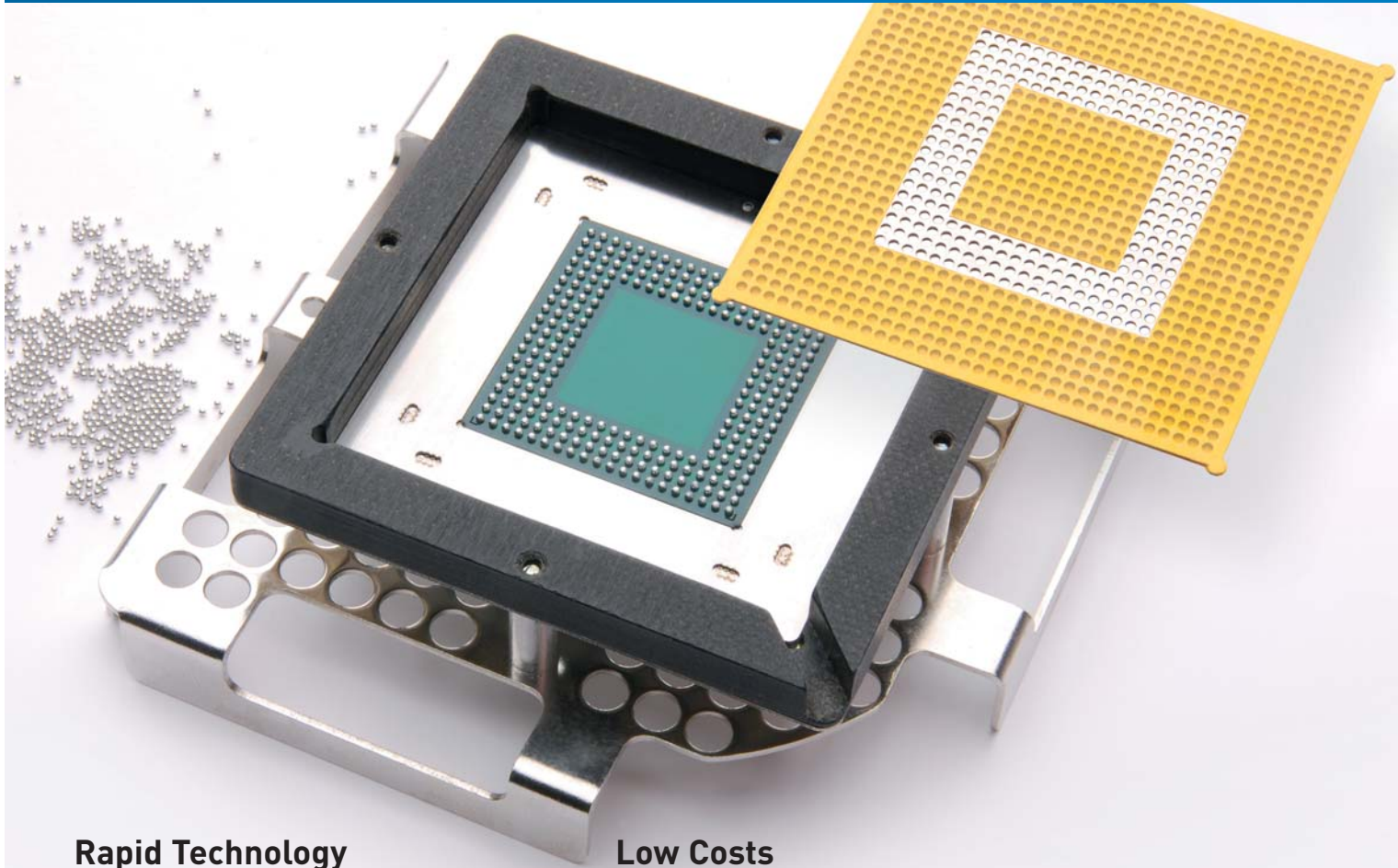


MARTIN Reball 3.1 / Prebump 3.1
Cost Effective Equipement
for Reballing and Prebumping
BGAs, CSPs and QFNs

Reballing for All

Thanks to many years of experience the MARTIN Reball 03.1 is an exceptionally economical and compact equipment. Whether for BGAs, CSPs or optionally also for QFNs: the MARTIN Reball 03.1 unit is suitable for the reworking of almost all package types. And at a price that suits even the smallest budget.

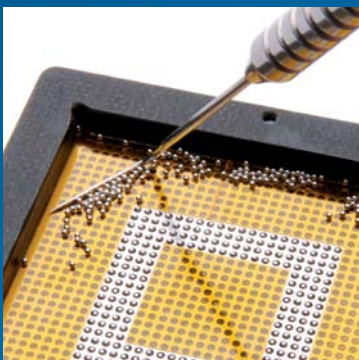


Rapid Technology

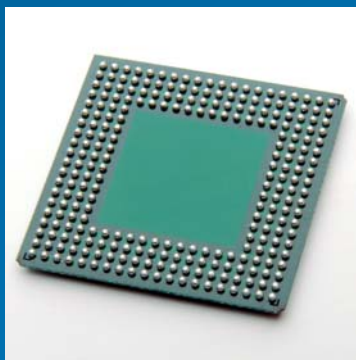
The safe and fast Rapid Technology utilises the permitted thermal limits of the SMD. The Components are heated at the highest permitted rate, and after that, maintain temperature at the recommended level. The result: a reballing process of only 3 minutes.

Low Costs

More than 25 years of know how pays for itself. The proven MARTIN technologies and interchangeable frames with adjustable eco masks significantly reduce the initial cost of investment. There is a 50% reduction, compared with previous reballing solutions.



Distribution of the balls on a prepared universal mask.



The reballled BGA is as good as new and ready for reuse.

Prebumping for Everyone

The new MARTIN Prebump 03.1 is especially designed for the prebumping of QFNs. With its newly developed Hotprint Technology high quality prebumping is now available to every user – even at the smallest pitches. An extensive range of accessories ensures that this comprehensive set is an all-rounder worthy of the well known MARTIN name.

Hotprint Technology

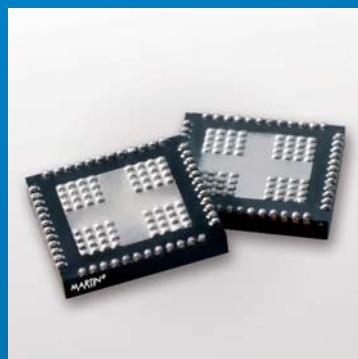
For this new process the mask is not removed after printing the solder paste, but remains on the QFN during reflow. This principle represents by far the most effective solution compared with other process methods while costing very little.

Precision Results

The MARTIN Prebump 03.1 succeeds by surprisingly simple handling, even when the smallest bumps at a pitch of only 0.4 mm can be applied very accurately. Trouble free rework with prebumped components is thus guaranteed.



Placement of mask and frame in the hotprinter.



The prebumped QFN is perfectly prepared for rework.



MARTIN Hot Reball 03 Control Unit

Basic equipment of the control unit

- SMD hook, brush, lens
- Kapton tape and cutter
- Solder balls, flux pen, flux creme
- Manual and Rework ABC (handbook)

Technical Details

| | |
|--------------------------|--------------------------------|
| Dimensions: | 140 x 290 x 83 mm |
| Power: | 50 - 500 Watt |
| Process temperature: | 210 - 260°C |
| Temperature measurement: | K type thermo couple, built in |
| Programs: | 11 |

MARTIN Reball 03.1

In addition the set comes complete with

- Eco holder 45 x 45 mm for BGAs
- 7 Eco adapter frames for BGAs from 15 x 15 to 40 x 40 mm
- 2 Eco reballing masks for all BGAs with 1.27 mm ball pitch



MARTIN Prebump 03.1

In addition the set comes complete with

- Prebumping hotprinter with holder
- Squeegee and tweezers
- Flux pen and solder paste for printing

Not included

Prebumping masks for QFNs and frames



Optional Extras

- Eco reballing masks for BGAs with nearly all ball pitches
- Eco adapter frames for special BGAs
- All types of consumables like solder balls, solder paste, flux pen, flux creme, cleaning fabric etc.
- Holder for all CSPs
- Reballing masks for CSPs
- Frames for CSPs and QFNs
- Prebumping masks for QFNs